

FIG. 1

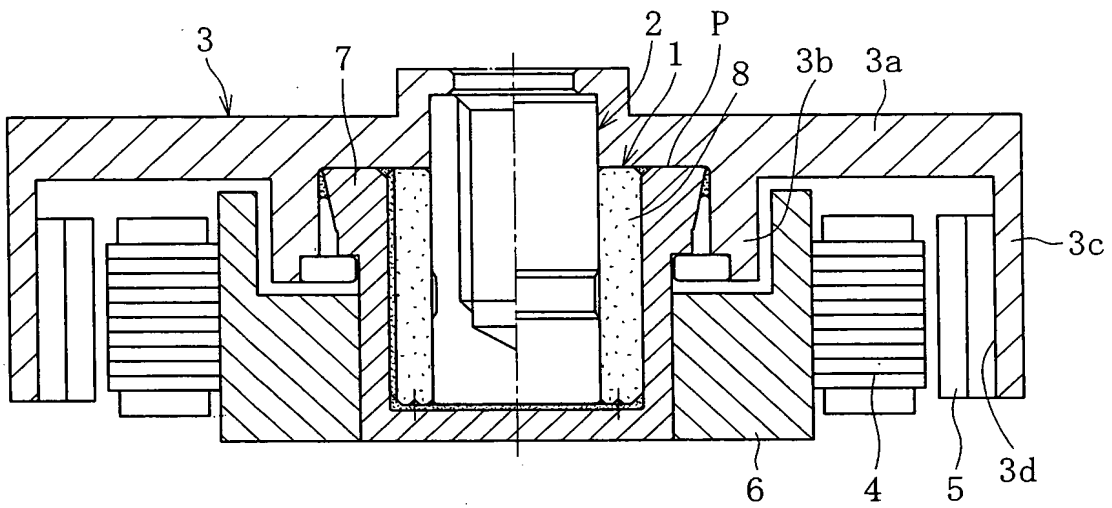


FIG. 2

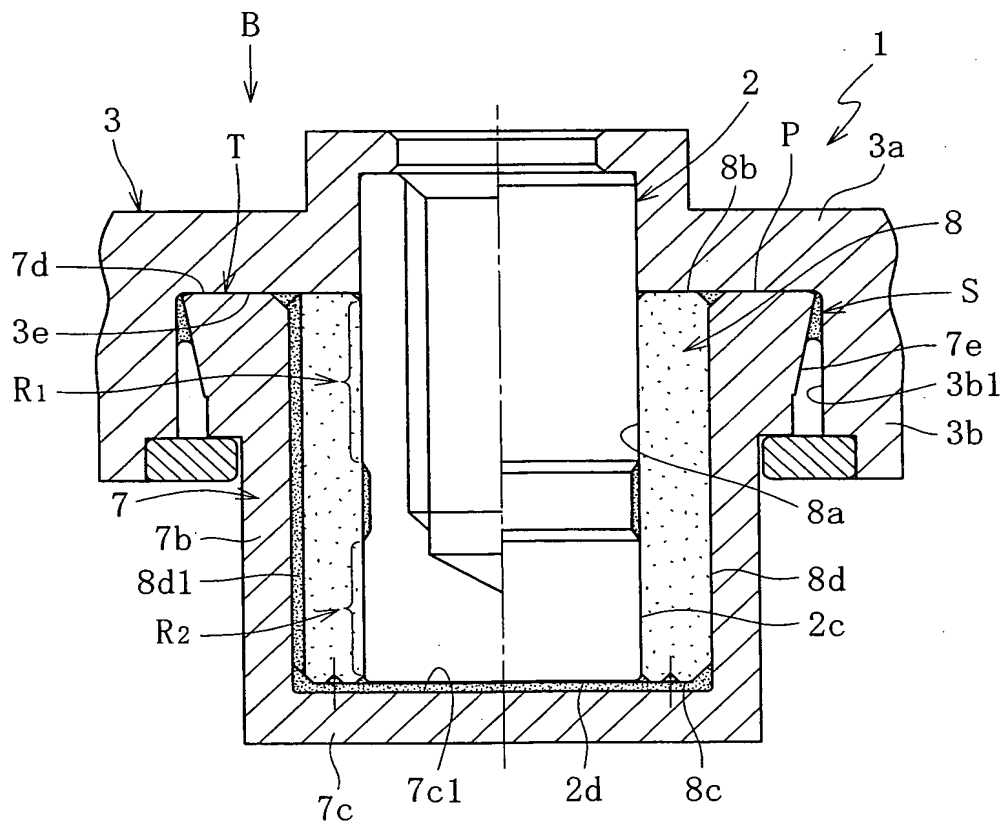


FIG. 3

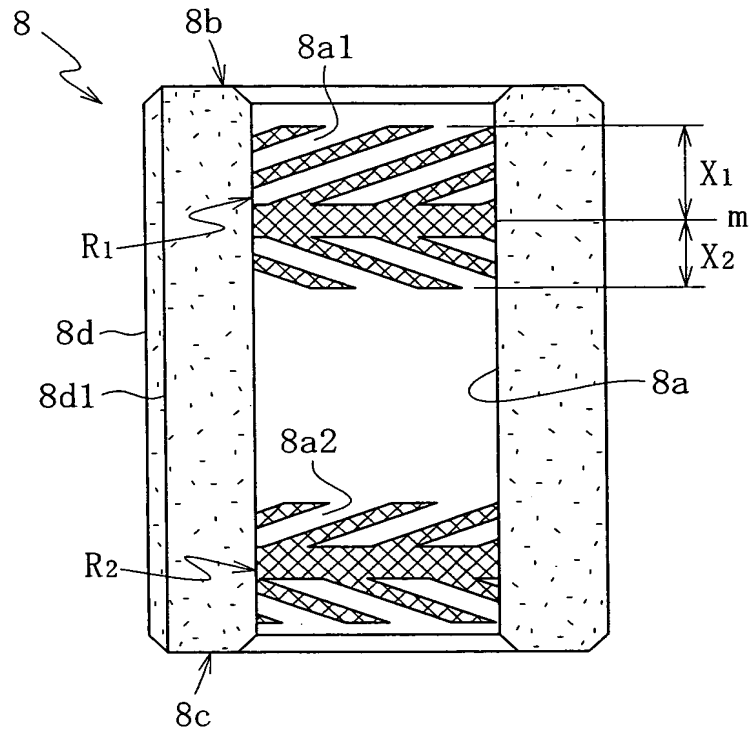


FIG. 4

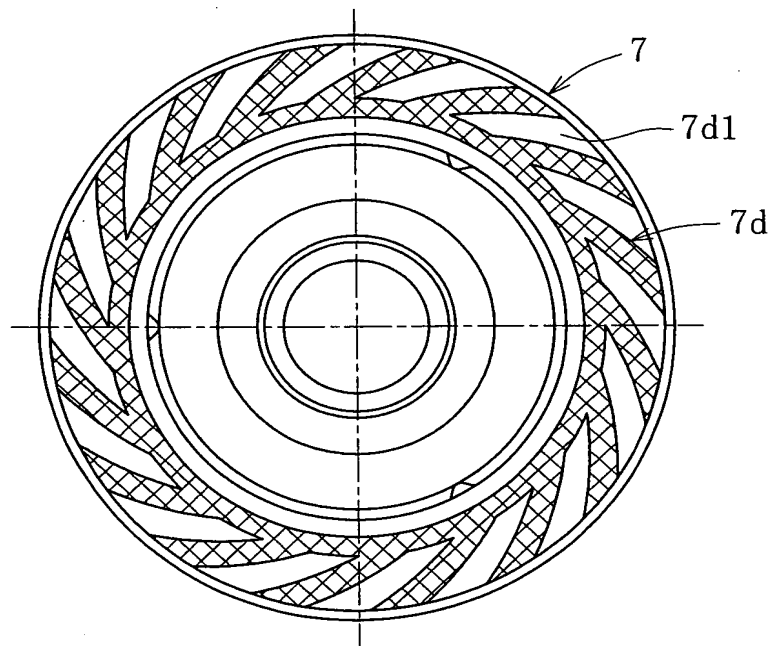


FIG. 5

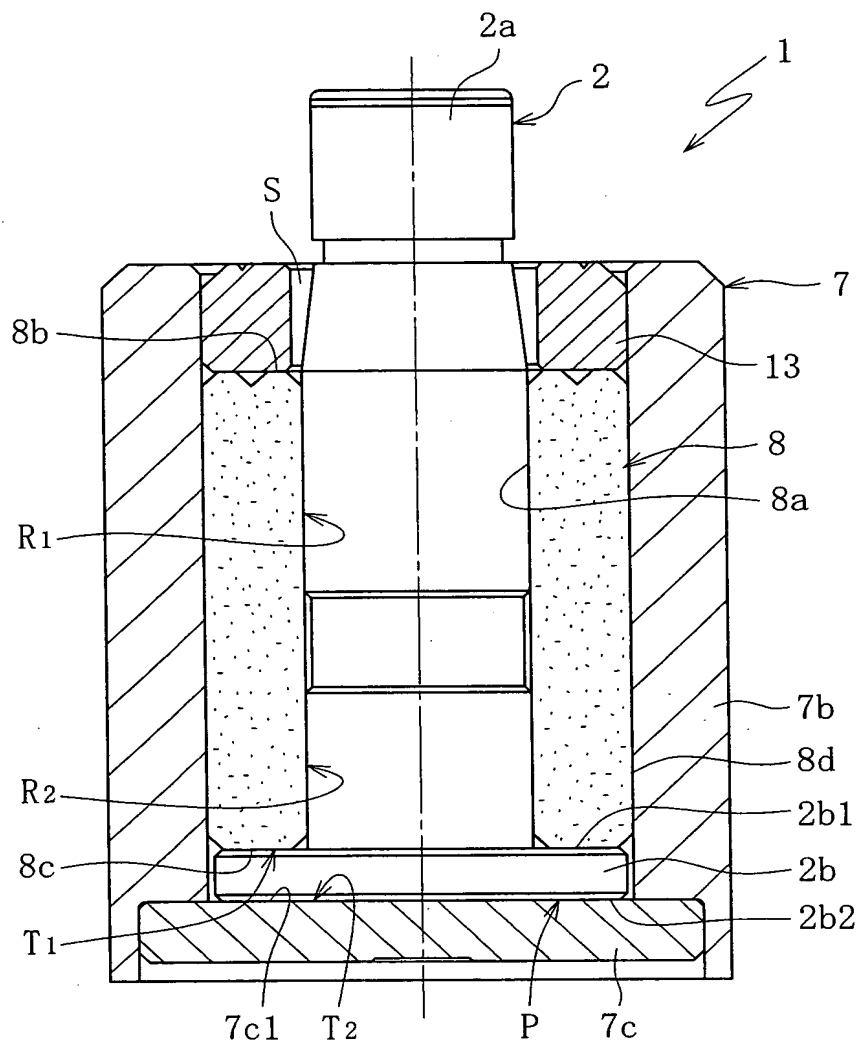


FIG. 6

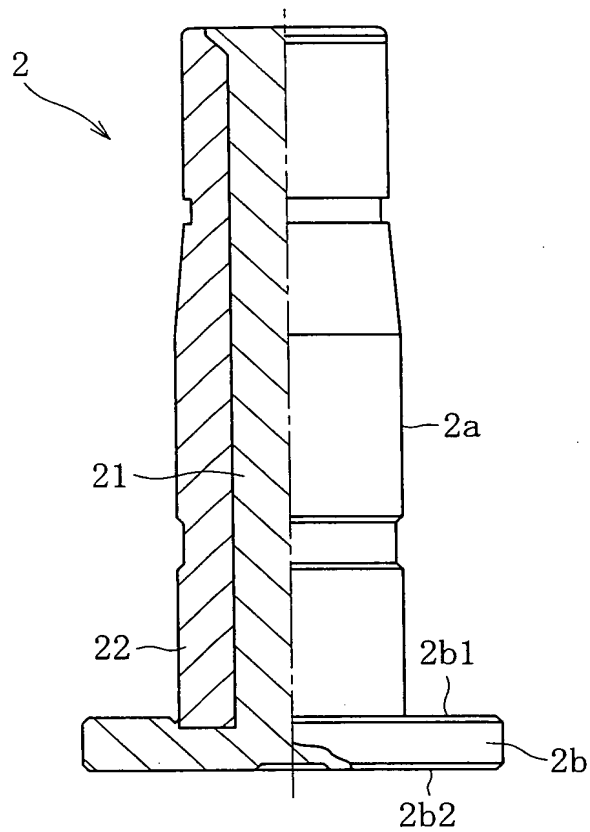


FIG. 7

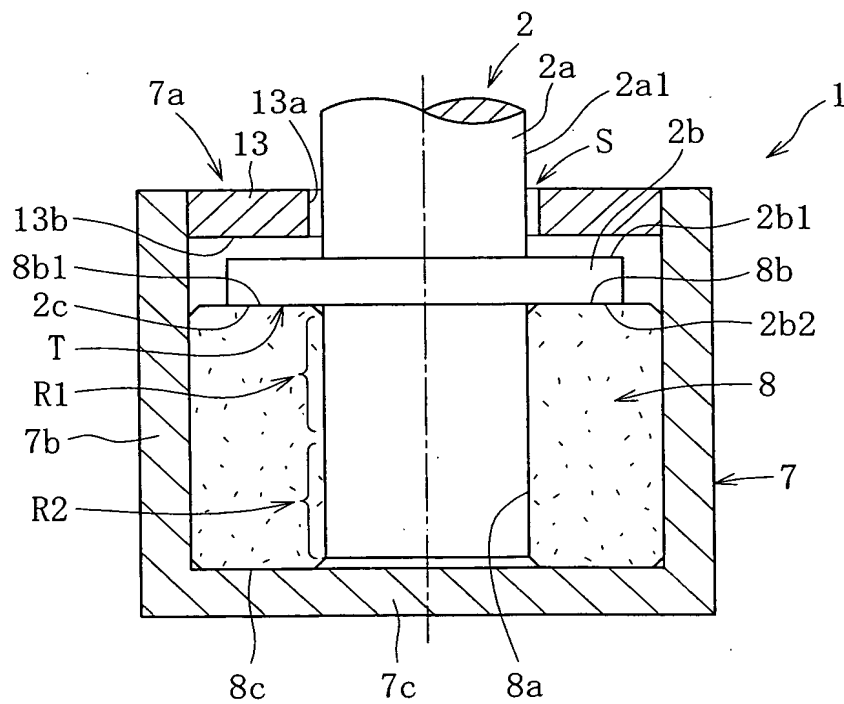


FIG. 8a

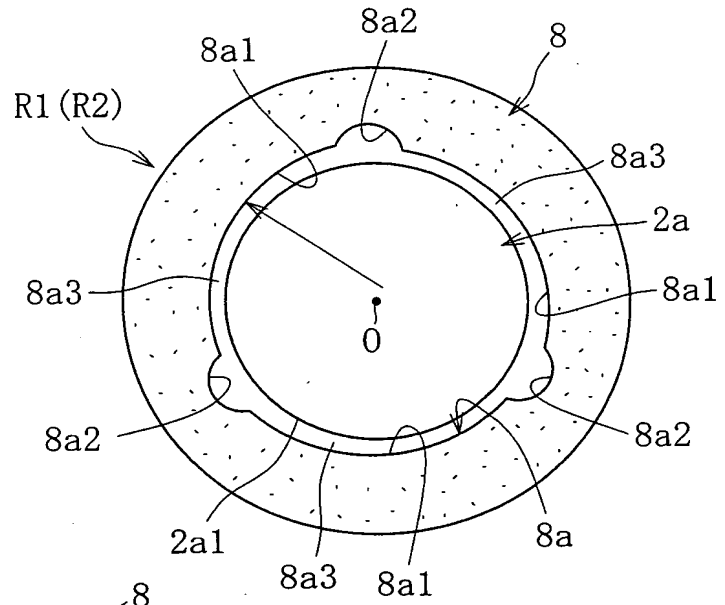


FIG. 8b

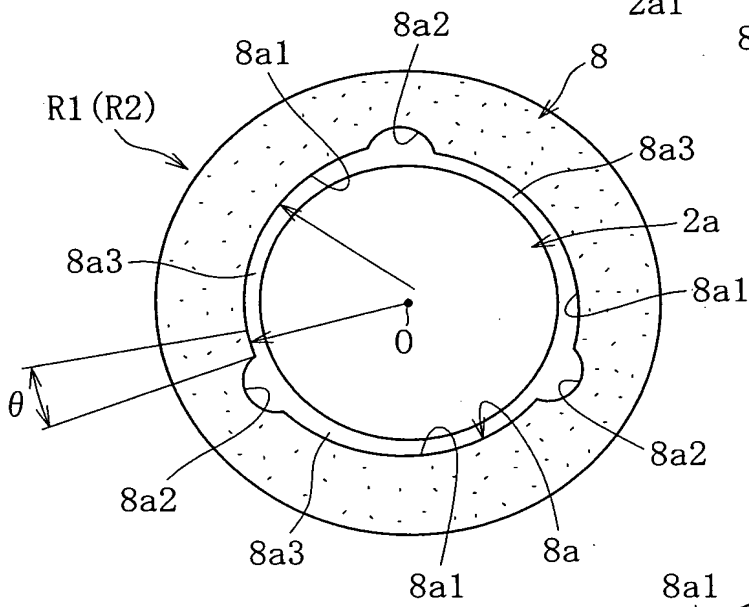
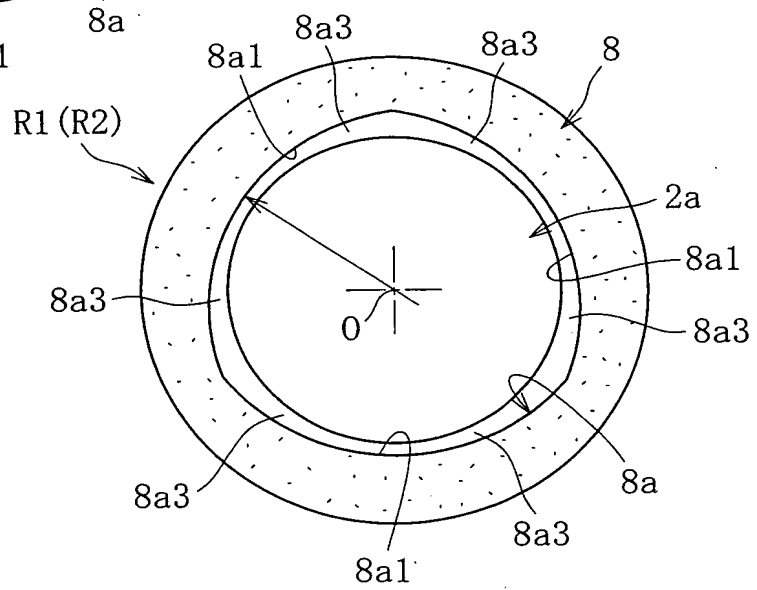


FIG. 8c



This cross-sectional diagram illustrates a multi-layered electronic component assembly. The assembly is built upon a base substrate 1. A central core 2 is surrounded by a layer 3. On the left side, a component 6 is mounted on a base 6a, with a layer 7b1 and a feature 7f1. A central vertical feature 7f2 is present. On the right side, a component 4 is mounted on a base 4a, with a layer 7b2 and a feature 7f2. A central vertical feature 7f1 is also shown. A layer 7 is located at the bottom of the central core area. A component 5 is mounted on the right side of the central core. A layer 8 is located at the bottom of the right side of the central core. A layer 9 is located at the top of the central core area.

FIG. 11a

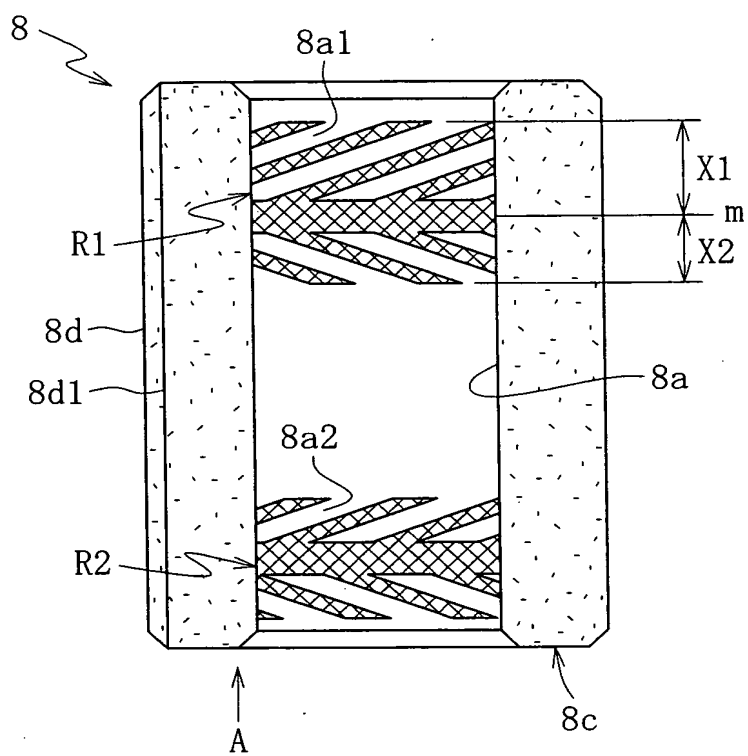


FIG. 11b

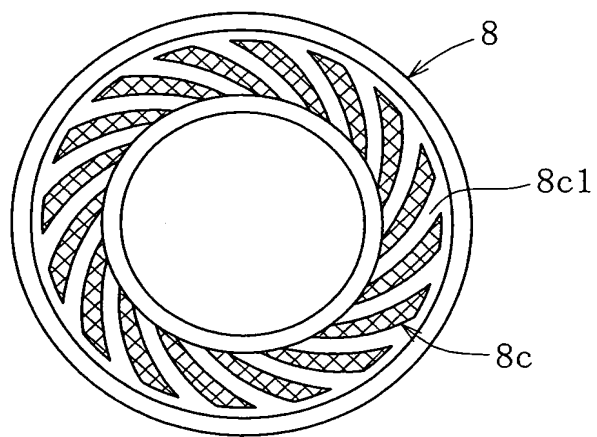


FIG. 12

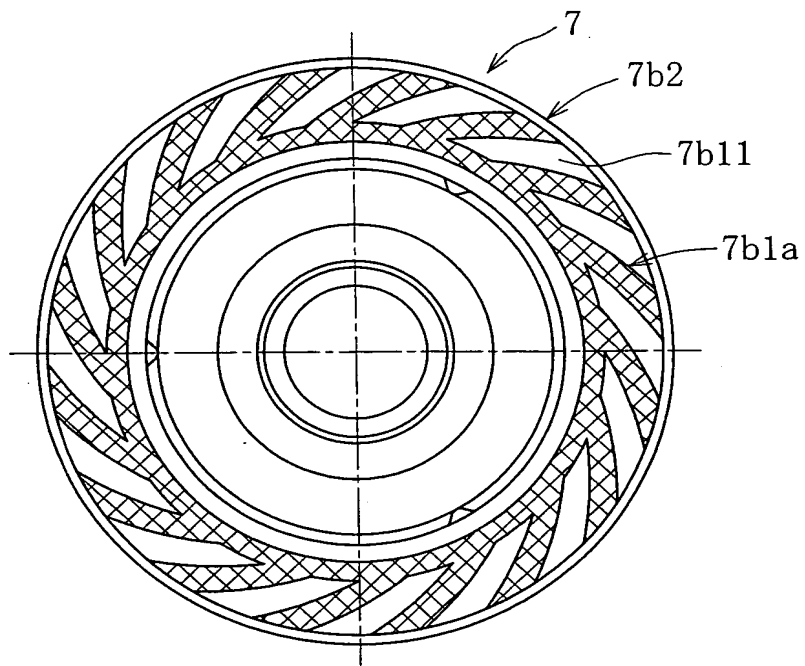


FIG. 13

